



QVE00033 Phototransistor Optical Surface Mount Interrupter Switch

Features

- No contact switching
- Transistor Output
- Compact surface mount package
- Opaque black plastic housing
- 2mm wide slot
- 0.4 mm aperture width
- Tape and reel
- Reflow conditions:

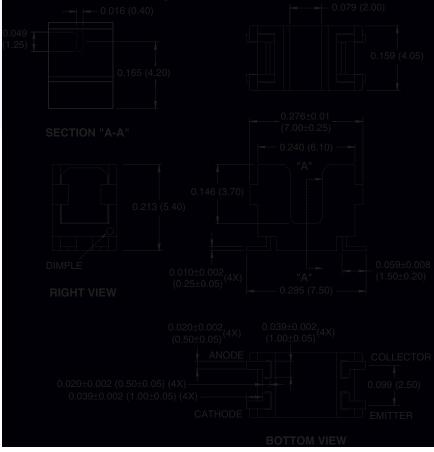
 Preheat = 160°C for 120 seconds

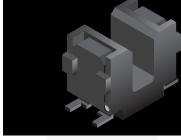
 Reflow = 200°C for 60 seconds (peak = 240°C)
- HL-94V-0 housing

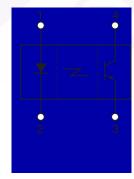
Description

The QVE00033 is a miniature slotted optical switch designed for surface mount applications. It consists of a GaAs LED and a silicon phototransistor facing each other across a 2mm gap, and packaged in a temperature resistant black plastic housing.

Package Dimension







Note:

1. Dimensions for all drawings are in inches (millimeters). Tolerance ±0.005" (0.127mm) unless othewise specified.

Absolute Maximum Ratings (T_A = 25°C unless otherwise specified)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating Units			
T _{OPR}	Operating Temperature	-55 to +100	°C		
T _{STG}	Storage Temperature	-55 to +100	°C		
T _{SOL-I}	Soldering Temperature (Iron) ^(2,3,4)	240 for 5 sec.	°C		
T _{SOL-F}	Soldering Temperature (Flow) ^(2,3)	260 for 10 sec.	°C		
P _{TOT}	Total Power Dissipation 100		mW		
EMITTER					
I _F	Continuous Forward Current	50	mA		
V _R	Reverse Voltage	6	V		
P _D	Power Dissipation ⁽¹⁾	75	mW		
SENSOR					
V _{CEO}	Collector-Emitter Voltage	30	V		
V _{ECO}	Emitter-Collector Voltage	4.5	V		
I _C	Collector Current	20	mA		
P _D	Power Dissipation ⁽¹⁾	75	mW		

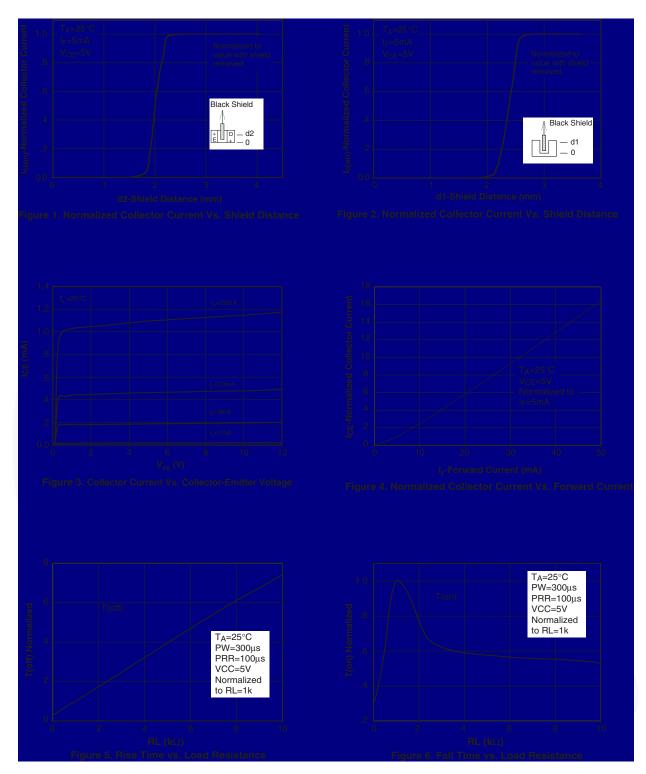
Notes:

- 1. Derate power dissipation linearly 1.00mW/°C above 25°C.
- 2. RMA flux is recommended.
- 3. Methanol or isopropyl alcohols are recommended as cleaning agents.
- 4. Soldering iron tip 1/16" (1.6mm) from housing.

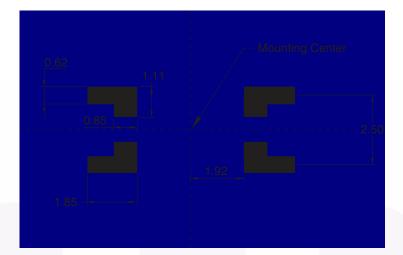
Electrical/Optical Characteristics (T_A = 25°C unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units		
EMITTER	EMITTER							
V _F	Forward Voltage	I _F = 20mA		1.2	1.4	V		
I _R	Reverse Current	V _R = 4V			10	μΑ		
I _{PE}	Peak Emission Wavelength	I _F = 20mA		940		nm		
SENSOR								
I _{CEO}	Dark Current	$V_{CE} = 20V, I_F = 0mA$			100	nA		
COUPLED								
I _{C(ON)}	Collector Current	$I_F = 5mA, V_{CE} = 5V$	100		600	μΑ		
V _{CE (SAT)}	Collector Emitter	$I_F = 10 \text{mA}, I_C = 40 \mu \text{A}$			0.4	V		
t _r	Rise Time	$V_{CC} = 5V, R_L = 1000\Omega,$		7	150	μs		
t _f	Fall Time	I _C = 100μA		7	150	μs		

Typical Performance Characteristics



Recommended Printed Circuit Board Pattern (For Reference Only)



Tape and Reel Dimensions







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